OMB No. 3117-0016/USITC No. 03-1-2040; Expiration Date: 6/30/05
(No response is required if currently valid OMB control number is not displayed)

PRODUCERS' QUESTIONNAIRE

DRAMS AND DRAM MODULES FROM KOREA

Return completed questionnaire to:

UNITED STATES INTERNATIONAL TRADE COMMISSION
Office of Investigations, Room 615
500 E Street, SW, Washington, DC 20436

So as to be received by the Commission by no later than May 9, 2003

The information called for in this questionnaire is for use by the United States International Trade Commission in connection with its countervailing duty investigation concerning DRAMs and DRAM modules from Korea (inv. No. 701-TA-431 (Final)). The information requested in the questionnaire is requested under the authority of the Tariff Act of 1930, title VII. This report is mandatory and failure to reply as directed can result in a subpoena or other order to compel the submission of records or information in your possession (19 U.S.C. § 1333(a)).

Name of firm _____

Address _____

City _____ **State** _____ **Zip code** _____

World Wide Web address _____

Has your firm produced DRAMs or DRAM modules (as defined in the instruction booklet) at any time since January 1, 2000?

☐ **NO** (Sign the certification below and promptly return only this page of the questionnaire to the Commission)

☐ **YES** (Read the instruction booklet carefully, complete all parts of the questionnaire, sign the certification, and return the entire questionnaire to the Commission)

CERTIFICATION

I certify that the information herein supplied in response to this questionnaire is complete and correct to the best of my knowledge and belief and understand that the information submitted is subject to audit and verification by the Commission.

By signing this certification I also grant consent for the Commission, and its employees and contract personnel, to use the information provided in this questionnaire and throughout this investigation in any other import-injury investigations conducted by the Commission on the same or similar merchandise. (If you do not consent to such use, please note the certification accordingly.)

I acknowledge that information submitted in this questionnaire response and throughout this investigation may be used by the Commission, its employees, and contract personnel who are acting in the capacity of Commission employees, for developing or maintaining the records of this investigation or related proceedings for which this information is submitted, or in internal audits and investigations relating to the programs and operations of the Commission pursuant to 5 U.S.C. Appendix 3. I understand that all contract personnel will sign non-disclosure agreements.

_____ _____
Name and Title of Authorized Official ***Date***

_____ ( ) _____ ( ) _____
Signature of Authorized Official ***Phone*** ***Fax***

PART I.--GENERAL QUESTIONS

The questions in this questionnaire have been reviewed with market participants to ensure that issues of concern are adequately addressed and that data requests are sufficient, meaningful, and as limited as possible. Public reporting burden for this questionnaire is estimated to average 60 hours per response, including the time for reviewing instructions, searching existing data sources, gathering the data needed, and completing and reviewing the questionnaire. Send comments regarding the accuracy of this burden estimate or any other aspect of this collection of information, including suggestions for reducing the burden, to the Office of Investigations, U.S. International Trade Commission, 500 E Street, SW, Washington, DC 20436.

I-1. Please report below the actual number of hours required and the cost to your firm of preparing the reply to this questionnaire and completing the form.

_____ hours _____ dollars

I-2. Provide the name and address of establishment(s) covered by this questionnaire (see page 3 of the instruction booklet for reporting guidelines). If your firm is publicly traded, please specify the stock exchange and trading symbol.

_____

_____

I-3. Do you support or oppose the petition? Please explain.

☐ Support ☐ Oppose ☐ Take no position

_____

As indicated at the top of the page, your response to this question will be treated as business proprietary. However, if the Commission's final determination in the investigation is affirmative and a countervailing duty order is issued, the Commission, pursuant to section 754 of the Tariff Act of 1930, will provide a list of firms supporting the petition to the Customs Service for possible distribution of any countervailing duties that may be collected. If you wish to waive business proprietary treatment of your response to this question in order to make your position with respect to the petition public and allow inclusion of your firm on that list, indicate "yes" below.

☐ Yes ☐ No (that is, I do not wish my position on the petition to be made public)

I-4. Is your firm owned, in whole or in part, by any other firm?

☐ No ☐ Yes--List the following information.

Firm name	Address	Extent of ownership

PART I.--GENERAL QUESTIONS--*Continued*

I-5. Does your firm have any related firms, either domestic or foreign, which are engaged in importing DRAMs or DRAM modules from Korea into the United States or which are engaged in exporting DRAMs or DRAM modules from Korea to the United States?

☐ No ☐ Yes--List the following information.

Firm name	Address	Affiliation

I-6. Does your firm have any related firms, either domestic or foreign, which are engaged in the production of DRAMs or DRAM modules?

☐ No ☐ Yes--List the following information.

Firm name	Address	Affiliation

PART II.--TRADE AND RELATED INFORMATION

Further information on this part of the questionnaire can be obtained from Mary Messer (202-205-3193). **Supply all data requested on a calendar-year basis.**

II-1. Who should be contacted regarding the requested trade and related information?

Company contact: _____
Name and title

_____ _____
Phone No. E-mail address

II-2. Has your firm experienced any plant openings, relocations, expansions, acquisitions, consolidations, closures, or prolonged shutdowns because of strikes or equipment failure; curtailment of production because of shortages of materials; or any other change in the character of your operations or organization relating to the production of DRAMs or DRAM modules since January 1, 2000?

☐ No ☐ Yes--Supply details as to the time, nature, and significance of such changes.

_____

_____

_____

PART II.--TRADE AND RELATED INFORMATION--*Continued*

II-3. (a) Does your firm produce other products (e.g., logic devices, SRAM modules, flash memory, etc.) on the same equipment and machinery used in the production of DRAMs or DRAM modules? Please distinguish between equipment used to produce DRAMs with a density of 64 meg and lower, and equipment used to produce DRAMs with a density of 128 meg and higher.

☐ No ☐ Yes--List the following information.

Product	Basis for allocation of capacity data

(b) Please provide the percent of your total wafer starts accounted for by DRAM wafers (regardless of density) for each of the following periods. 2000 _____; 2001 _____; 2002 _____; Jan.-Mar. 2002 _____; Jan.-Mar. 2003 _____

(c) Please provide the share (in percent) of your total assembly capability accounted for by cased DRAMs (regardless of density) in each of the following periods. 2000 _____; 2001 _____; 2002 _____; Jan.-Mar. 2002 _____; Jan.-Mar. 2003 _____

II-4. Please describe the constraint(s) that set the limit(s) on your production capabilities, reporting specifically for design, wafer fabrication, assembly, and testing.

II-5. Does your firm produce other products (e.g., logic devices, SRAM modules, flash memory) using the same production and related workers employed to produce DRAMs or DRAM modules?

☐ No ☐ Yes--List the following information.

Product	Basis for allocation of employment data

II-6. Is your firm able to switch production between DRAMs/DRAM modules and other products in response to a relative change in the price of DRAMs/DRAM modules vis-a-vis the price of other products, using the same equipment and labor?

☐ No ☐ Yes--Please identify below the other products, the approximate time and cost involved in switching, and the minimum relative price change required for your firm to switch production to or from DRAMs/DRAM modules.

PART II.--TRADE AND RELATED INFORMATION--*Continued*

II-7. Since January 1, 2000, has your firm been involved in a toll agreement (see definition in the instruction booklet) regarding the production of DRAMs or DRAM modules?

☐ No ☐ Yes--Name firm: _____

II-8. Does your firm produce DRAMs or DRAM modules in a foreign trade zone (FTZ)?

☐ No ☐ Yes--Identify FTZ(s): _____

II-9. Since January 1, 2000, has your firm imported DRAMs or DRAM modules?

☐ No ☐ Yes--***COMPLETE AND RETURN THE ENCLOSED IMPORTERS' QUESTIONNAIRE***

II-10. The following questions relate to your firm's captive consumption of DRAMs or DRAM modules, in the production of downstream product(s). **NOTE**.--For purposes of this question, do not report cased DRAMs as a downstream product of uncased DRAMs, or DRAM modules as a downstream product of cased DRAMs.

(a) Does your firm internally transfer or sell to any related firm, any portion of its production of DRAMs or DRAM modules for use in the production of downstream product(s)?

☐ No–Skip to question II-11. ☐ Yes–Complete the questions below.

(b) Please identify the downstream product(s) in the production of which your firm, or related firm, captively consumes DRAMs or DRAM modules. Use additional pages as necessary.

_____

_____

(c) Please report the percentage of your firm's production of DRAMs or DRAM modules that was used in the production of downstream product(s) by your firm or related firm in the following periods.
2000:_____%; 2001:_____%; 2002:_____%; and Jan.-Mar. 2003_____%.

(d) Do the downstream product(s) for which your firm internally transfers or captively consumes DRAMs or DRAM modules compete for sales in the merchant market with DRAMs or DRAM modules? Please explain your answers.

_____

_____

_____

PART II.--TRADE AND RELATED INFORMATION--*Continued*

II-11. Describe the significance of the antidumping duty order covering imports of non-Samsung Korean DRAMs $ 1-Meg and DRAM modules containing any DRAMs $ 1-Meg that was in effect from May 10, 1993, until October 5, 2000, in terms of its effect, either directly or indirectly, on your firm with regard to the below listed items and any others you consider appropriate. You may wish to compare your firm's operations before and after the imposition of the order, and before and after the revocation of the order. If appropriate, include a discussion of the effect(s), if any, of changes in the dumping margins. Attach additional pages, as needed.

(a) Production capacity, production, shipments, inventories, purchases, and employment:

_____

_____

_____

(b) Return on investment, ability to generate capital to finance the modernization of U.S. plant(s) and equipment, or ability to maintain existing levels of expenditures for research and development.

_____

_____

_____

II-12. Please indicate the DRAM/DRAM module products that your firm produces in the United States, and indicate whether your production is for the merchant market or for captive consumption. CHECK ALL THAT APPLY. Note.--"3rd country" refers to countries other than Korea and the United States

Merchant market	Captive consumption	Product
_____	_____	Uncased DRAMs (fabricated dice)
_____	_____	Cased DRAMs from U.S.-fabricated dice
_____	_____	Cased DRAMs from Korean-fabricated dice
_____	_____	Cased DRAMs from all-other-source-fabricated dice
		DRAM modules made from cased DRAMs that were cased in–
_____	_____	The United States from U.S.-fabricated dice
_____	_____	Korea from U.S.-fabricated dice
_____	_____	3rd countries from U.S.-fabricated dice
_____	_____	The United States from Korean-fabricated dice
_____	_____	Korea from Korean-fabricated dice
_____	_____	3rd countries from Korean-fabricated dice
_____	_____	The United States from 3rd-country-fabricated dice
_____	_____	Korea from 3rd-country-fabricated dice
_____	_____	3rd countries from 3rd-country-fabricated dice

PART II.--TRADE AND RELATED INFORMATION--*Continued*

II-13. **ALL DRAMS**.--For your U.S. establishment(s) wherein DRAM wafers are fabricated (UNCASED DRAMS), assembled (CASED), and/or assembled into modules, report the average-of-period full production capabilities (i.e., capacity--see definitions in instructions booklet). In reporting the capacity and wafer starts requested below for UNCASED DRAMS, please consider the capacity utilization (i.e., wafer starts divided by capacity) experienced by your U.S. establishments wherein DRAM wafers are fabricated. Also, estimate for each period the probe yield (i.e., the percentage of usable die per wafer). For CASED DRAMS and DRAM modules, please consider the capacity utilization (i.e., assembly divided by assembly capacity) of your DRAM/DRAM module assembly facilities.

Item	Calendar years			January-March	
	2000	2001	2002	2002	2003
UNCASED DRAMS:[1] Average capacity[2] (*1,000 8-inch-equivalent wafers*)					
Wafer starts (*1,000 8-inch-equivalent wafers*)					
Probe yield (*percent*)					
CASED DRAMS: Average capacity[3] (*1,000 units*)					
Assembly[4] (*1,000 units*)					
DRAM MODULES: Average capacity[5] (*1,000 units*)					
Assembly (*1,000 units*)					

[1] Report your capacity and production on an 8-inch-equivalent basis. However, indicate the size(s) (in inches) of silicon wafers actually used by your firm in the production of DRAMs. _____

[2] The average capacity reported is based on operating _____ hours per week, _____ weeks per year. Briefly explain assumptions made and methods used in calculating the estimates reported above for practical capacity to fabricate DRAM wafers. Also explain any changes in reported capacity. Use additional pages as necessary. _____

[3] The average capacity reported is based on operating _____ hours per week, _____ weeks per year. Briefly explain assumptions made and methods used in calculating the estimates reported above for average capacity to assemble DRAMs. Also explain any changes in reported capacity. Use additional pages as necessary. _____

[4] The data reported for all DRAMs assembled should equal the totals of production for all densities of all cased DRAMs reported in question II-15. If data do not reconcile, please explain, using additional pages as necessary. ____

[5] The average capacity reported is based on operating _____ hours per week, _____ weeks per year. Briefly explain assumptions made and methods used in calculating the estimates reported above for average capacity to assemble DRAM modules. Also explain any changes in reported capacity. Use additional pages as necessary. ____

PART II.--TRADE AND RELATED INFORMATION--*Continued*

II-14. **UNCASED DRAMS FABRICATED IN THE UNITED STATES.--**Report your firm's production, shipments, and inventories related to the production of uncased DRAMs in your U.S. establishment(s) during the specified periods. **Report separately for each density of DRAM your firm produces, photocopying this page as necessary. Identify the density reported on each page by checking the appropriate box.** (See definitions in the instruction booklet.)

☐ 16 Meg ☐ 64 Meg ☐ 128 Meg ☐ 256 Meg ☐ 512 Meg ☐ Other (specify density _____)

Item	Calendar years			January-March	
	2000	2001	2002	2002	2003
Beginning-of-period inventories (*1,000 units*)					
PRODUCTION:[1] Quantity (*1,000 units*)					
Value[2] (*$1,000*)					
U.S. SHIPMENTS: U.S. company transfers/internal consumption for making cased DRAMs: Quantity (*1,000 units*)					
Value[3] (*$1,000*)					
Other U.S. company transfers (please identify the nature of the transfers: _____) Quantity (*1,000 units*)					
Value[3] (*$1,000*)					
Domestic commercial shipments:[4] Quantity (*1,000 units*)					
Value (*$1,000*)					
EXPORT SHIPMENTS: Company transfers to foreign affiliates:[5] Quantity (*1,000 units*)					
Value[3] (*$1,000*)					
Other export shipments:[6] Quantity (*1,000 units*)					
Value (*$1,000*)					
End-of-period inventories[7] (*1,000 units*)					

[1] Reported production should include only usable units (i.e., net of any losses that occur during wafer fabrication and sorting).

[2] Please report the cost of production.

[3] Internal consumption and transfers to related firms must be valued at fair market value. In the event that you use a different basis for valuing these transactions, please specify that basis (e.g., cost, cost plus, etc.) and provide value data using that basis for 2000, 2001, 2002, and January-March 2003. _____

[4] List your customers: _____

[5] Identify foreign affiliate(s) and location(s). _____
Specify the form(s) in which your uncased DRAMs were exported (e.g., uncut wafers, bare die, etc.). _____

[6] Identify your principal export markets: _____
Specify the form(s) in which your uncased DRAMs were exported (e.g., uncut wafers, bare die, etc.). _____

[7] Reconciliation of data.--Please note that the **quantities** reported above should reconcile as follows: beginning-of-period inventories, plus production, less total shipments, equals end-of-period inventories. Do the data reported reconcile?
☐ Yes ☐ No--Please explain: _____

PART II.--TRADE AND RELATED INFORMATION--*Continued*

II-15. **CASED DRAMS ASSEMBLED IN THE UNITED STATES.--**Report your firm's assembly, shipments, and inventories related to the assembly of cased DRAMs in your U.S. establishment(s) during the specified periods. (See definitions in the instruction booklet.) **Report separately for each density of DRAM your firm assembles, by the location of the fabrication of the dice, photocopying this page as necessary. Identify: (1) the density, and (2) the dice fabrication location (if Korea, report separately for Samsung dice) reported on each page by checking one box per category below.**

1) Density: ☐ 16 Meg ☐ 64 Meg ☐ 128 Meg ☐ 256 Meg ☐ 512 Meg ☐ Other (specify density: _____)

2) Dice fabrication location: ☐ U.S. ☐ Korea (Samsung) ☐ Korea (other firms) ☐ Other locations (specify: _____)

Item	Calendar years			January-March	
	2000	2001	2002	2002	2003
Beginning-of-period inventories (*1,000 units*)					
Production (assembly):[1] Quantity (*1,000 units*)					
Value[2] (*$1,000*)					
U.S. SHIPMENTS: **U.S. company transfers/internal consumption for making DRAM modules:** Quantity (*1,000 units*)					
Value[3] (*$1,000*)					
Other U.S. company transfers (please identify the nature of the transfers: _____) Quantity (*1,000 units*)					
Value[3] (*$1,000*)					
Domestic commercial shipments: Quantity (*1,000 units*)					
Value (*$1,000*)					
EXPORT SHIPMENTS: **Company transfers to foreign affiliates:**[4] Quantity (*1,000 units*)					
Value[3] (*$1,000*)					
Other export shipments:[5] Quantity (*1,000 units*)					
Value (*$1,000*)					
End-of-period inventories[6] (*1,000 units*)					

[1] Reported production should include only usable units (i.e., net of any losses that occur during assembly and testing). In addition, reported production should include assembly of all dice, whether internally transferred or imported or otherwise purchased.

[2] Please report the cost of production.

[3] Internal consumption and transfers to related firms must be valued at fair market value. In the event that you use a different basis for valuing these transactions, please specify that basis (e.g., cost, cost plus, etc.) and provide value data using that basis for 2000, 2001, 2002, and January-March 2003 below:

_____

[4] Identify foreign affiliate(s) and location(s). _____

[5] Identify your principal export markets: _____

[6] Reconciliation of data.--Please note that the **quantities** reported above should reconcile as follows: beginning--of-period inventories, plus production, less total shipments, equals end-of-period inventories. Do the data reported reconcile? ☐ Yes ☐ No--Please explain: _____

PART II.--TRADE AND RELATED INFORMATION--*Continued*

II-16. **DRAM MODULES ASSEMBLED IN THE UNITED STATES.--**Report your firm's assembly, shipments, and inventories related to the assembly of DRAM modules in your U.S. establishment(s) during the specified periods. (See definitions in the instruction booklet.) **Report separately for each dice fabrication location/cased DRAMs assembly location combination. Photocopy this page as necessary, checking one box per category for the: (1) dice fabrication location (if Korea, report separately for Samsung dice), and (2) cased DRAM assembly location reported on each page.**

1) Dice fabrication location: ☐ U.S. ☐ Korea (Samsung) ☐ Korea (other firms) ☐ Other locations (specify: _____)

2) Cased DRAMs assembly location: ☐ United States ☐ Korea ☐ Other locations (specify: _____)

Item	Calendar years			January-March	
	2000	2001	2002	2002	2003
Beginning-of-period inventories (*billion bits*)					
Production (assembly):[1] Quantity (*billion bits*)					
Value[2] (*$1,000*)					
U.S. SHIPMENTS: Internal consumption/other U.S. company transfers (please identify the nature of the consumption/transfers: _____) Quantity (*billion bits*)					
Value[3] (*$1,000*)					
Domestic commercial shipments: Quantity (*billion bits*)					
Value (*$1,000*)					
EXPORT SHIPMENTS: Company transfers to foreign affiliates:[4] Quantity (*billion bits*)					
Value[3] (*$1,000*)					
Other export shipments:[5] Quantity (*billion bits*)					
Value (*$1,000*)					
End-of-period inventories[6] (*billion bits*)					

[1] Report only usable modules (i.e., net of any losses that occur during assembly and testing).

[2] Please report the cost of production.

[3] Internal consumption and transfers to related firms must be valued at fair market value. In the event that you use a different basis for valuing these transactions, please specify that basis (e.g., cost, cost plus, etc.) and provide value data using that basis for 2000, 2001, 2002, and January-March 2003 below:

_____

[4] Identify foreign affiliate(s) and location(s). _____

[5] Identify your principal export markets: _____

[6] Reconciliation of data.--Please note that the **quantities** reported above should reconcile as follows: beginning-of-period inventories, plus production, less total shipments, equals end-of-period inventories. Do the data reported reconcile?

☐ Yes ☐ No--Please explain: _____

PART II.--TRADE AND RELATED INFORMATION--*Continued*

II-17. If you reported transfers to related firms in questions II-14, II-15, or II-16, please indicate the nature of the relationship between your firm and the related firms (e.g., joint venture, wholly owned subsidiary), whether the transfers were priced by market or by a non-market formula, whether your firm retained marketing rights to all transfers, and whether the related firms also processed inputs from sources other than your firm.

_____

_____

II-18 (a) In the following table, please estimate the shares (in percent) of the value of your 2002 U.S. shipments of DRAMs and DRAM modules, by DRAM type and by location of dice fabrication.

Type of DRAM	Dice fabricated in--				
	United States	Korea by--		Other sources	All sources
		Samsung	Other		
Standard DRAMs, including extended data out (EDO), fast page, synchronous, and double data rate					
Rambus					
Other DRAM types, including video (VRAM), synchronous graphics (SGRAM), windows (WRAM), and other (please specify type(s)): _____ _____ _____					
Total, all DRAMs					100.0

(b) In reference to the data provided in II-18a, please note general changes (if any) in your DRAM product mix or source mix that transpired during January 2000-March 2003. _____

_____

II-19. How much of the cost (raw materials, labor, and factory overhead, including depreciation of capital assets) of your firm's production of cased DRAMs is in the assembly process versus the fabrication process (or cost of purchasing uncased DRAMs)? If the share changes at different times in the DRAM life cycle, so specify.

	Average	New products	Legacy products
Fabrication/purchase of uncased DRAMs	_____ %	_____ %	_____ %
Assembly into cased DRAMs	_____ %	_____ %	_____ %
Total	100.0 %	100.0 %	100.0 %

II-20. How much of the cost of your firm's production of DRAM modules is in the assembly into modules process versus the production/purchase of cased DRAMs? If the share changes at different times in the DRAM life cycle, so specify.

	Average	New products	Legacy products
Production/purchase of cased DRAMs	_____ %	_____ %	_____ %
Assembly into modules	_____ %	_____ %	_____ %
Total	100.0 %	100.0 %	100.0 %

PART II.--TRADE AND RELATED INFORMATION--*Continued*

II-21. **CASED DRAMS MADE FROM U.S.-FABRICATED DICE ASSEMBLED BY FOREIGN AFFILIATES/SUBCONTRACTORS.--**Report your firm's foreign affiliates/subcontractors' shipments of cased DRAMs containing U.S. fabricated dice to the United States, and to other markets (including both shipments to the "home-market country" in which the cased DRAMs are assembled and shipments to other (non-U.S.) country markets). **Report separately for each density of cased DRAMs assembled by your firm and by the foreign location where the cased DRAMs are assembled (Korea or 3rd countries (i.e., countries other than Korea and the United States)), photocopying this page as necessary. Identify the density reported for each page by checking one box, below, per page.**

Density: ☐ 16 Meg ☐ 64 Meg ☐ 128 Meg ☐ 256 Meg ☐ 512 Meg ☐ Other (specify density _____)

Item	Calendar years			January-March	
	2000	2001	2002	2002	2003
CASED DRAMS ASSEMBLED IN KOREA: **Shipments to the United States:**[1] Quantity (*1,000 units*)					
Value (*$1,000*)					
U.S. export component value[2] (*$1,000*)					
Internally consumed by your firm outside the U.S. to produce DRAM modules:[3] Quantity (*1,000 units*)					
Value (*$1,000*)					
U.S. export component value[2] (*$1,000*)					
All other shipments, combined:[4] Quantity (*1,000 units*)					
Value (*$1,000*)					
U.S. export component value[2] (*$1,000*)					
CASED DRAMS ASSEMBLED IN 3RD COUNTRIES: **Shipments to the United States:**[5] Quantity (*1,000 units*)					
Value (*$1,000*)					
U.S. export component value[2] (*$1,000*)					
Internally consumed by your firm outside the U.S. to produce DRAM modules:[3] Quantity (*1,000 units*)					
Value (*$1,000*)					
U.S. export component value[2] (*$1,000*)					
All other shipments, combined:[6] Quantity (*1,000 units*)					
Value (*$1,000*)					
U.S. export component value[2] (*$1,000*)					

[1] List the major customers of your shipments to the United States of cased DRAMs assembled in Korea. _____

[2] The U.S. export value of the U.S.-fabricated uncased DRAMs used in the production of the cased DRAMs.

[3] Report shipments of these modules in question II-22.

[4] Including company transfers; list your major markets for cased DRAMs assembled in Korea. _____

[5] List your major customers of your shipments to the United States of cased DRAMs assembled in 3rd countries. _____

[6] Including company transfers; list your major markets for cased DRAMs assembled in 3rd countries. _____

PART II.--TRADE AND RELATED INFORMATION--*Continued*

II-22. **DRAM MODULES ASSEMBLED BY FOREIGN AFFILIATES/SUBCONTRACTORS FROM U.S.-FABRICATED DICE AND/OR 3RD-COUNTRY DICE ASSEMBLED INTO CASED DRAMS IN THE UNITED STATES.--**Report your firm's foreign affiliates/subcontractors' shipments of DRAM modules containing (1) U.S. fabricated dice, regardless of where assembled into cased DRAMs, or (2) cased DRAMs assembled in the United States from 3rd-country-fabricated dice (i.e., non-Korean and non-U.S. fabrication); identify whether these shipments are to the United States or to other markets (including both shipments to the "home-market country" in which the DRAM modules are assembled and shipments to other (non-U.S.) country markets). **Report separately for each dice fabrication/cased DRAM assembly combination indicated. Photocopy page as needed.**

☐ Cased DRAMs assembled in the United States from U.S.-fabricated dice

☐ Cased DRAMs assembled in Korea from U.S.-fabricated dice

☐ Cased DRAMs assembled in 3rd countries (those other than Korea and the United States) from U.S.-fabricated dice

☐ Cased DRAMs assembled in the United States from dice fabricated in 3rd countries

Item	Calendar years			January-March	
	2000	2001	2002	2002	2003
DRAM MODULES ASSEMBLED IN KOREA: **Shipments to the United States:**[1] Quantity (*billion bits*)					
Value (*$1,000*)					
U.S. export component value[2] (*$1,000*)					
All other shipments, combined:[3] Quantity (*billion bits*)					
Value (*$1,000*)					
U.S. export component value[2] (*$1,000*)					
DRAM MODULES ASSEMBLED IN 3RD COUNTRIES: **Shipments to the United States:**[4] Quantity (*billion bits*)					
Value (*$1,000*)					
U.S. export component value[2] (*$1,000*)					
All other shipments, combined:[5] Quantity (*billion bits*)					
Value (*$1,000*)					
U.S. export component value[2] (*$1,000*)					

[1] List your major customers of your shipments to the United States of DRAM modules assembled in Korea. _____

[2] The U.S. export value of U.S.-cased DRAMs plus the U.S. export value of U.S.-fabricated uncased DRAMs that were assembled into cased DRAMs by your foreign affiliates/subcontractors in Korea or 3rd countries (which should have been reported on the previous page).

[3] Including your company transfers; list your major markets for DRAM modules assembled in Korea. _____

[4] List your major customers of your shipments to the United States of DRAM modules assembled in 3rd countries. _____

[5] Including your company transfers; list your major markets for DRAM modules assembled in 3rd countries. _____

PART II.--TRADE AND RELATED INFORMATION--*Continued*

II-23. **PURCHASES OF UNCASED DRAMS OTHER THAN IMPORTS.--**Other than direct imports, has your firm purchased uncased DRAMs since January 1, 2000? (See definitions in the instruction booklet.)

☐ No ☐ Yes.--Report such purchases below for the specified periods. **Report separately for each density your firm purchases, by source of dice fabrication and by your use of the product, photocopying this page as necessary.** Identify: (1) the density, and (2) your use of the product, by checking one box each for category 1 and 2 below.

1) Density: ☐ 16 Meg ☐ 64 Meg ☐ 128 Meg ☐ 256 Meg ☐ 512 Meg ☐ Other (specify density _____)

2) Use of product: ☐ For cased DRAM production ☐ For resale ☐ For other uses (specify: _____)

Item	Calendar years			January-March	
	2000	2001	2002	2002	2003
PURCHASES OF UNCASED DRAMS, BY ORIGIN OF DICE:[1] [2]					
U.S.-fabricated dice: Quantity (*1,000 units*)					
Value (*$1,000*)					
Korean (Samsung)-fabricated dice: Quantity (*1,000 units*)					
Value (*$1,000*)					
Korean (other firms)-fabricated dice: Quantity (*1,000 units*)					
Value (*$1,000*)					
Other-source fabricated dice: Quantity (*1,000 units*)					
Value (*$1,000*)					

[1] Please indicate your reasons for purchasing this product. If your reasons differ by source, please elaborate.

_____

_____

_____

_____

_____

[2] Please list the name of the firm(s) from which you purchased this product. If your suppliers differ by source, please identify the source for each listed supplier. _____

_____

_____

_____

_____

_____

PART II.--TRADE AND RELATED INFORMATION--*Continued*

II-24. **PURCHASES OF CASED DRAMS OTHER THAN IMPORTS.--**Other than direct imports, has your firm purchased cased DRAMs since January 1, 2000? (See definitions in the instruction booklet.)

☐ No ☐ Yes.--Report such purchases below for the specified periods. **Report separately for each density your firm purchases, by source of dice fabrication, by location of cased DRAM assembly, and by your use of the product, photocopying this page as necessary.** Identify: (1) the density, and (2) location of cased DRAM assembly, and (3) your use of the product, by checking one box each for category 1, 2, and 3 below.

1) Density: ☐ 16 Meg ☐ 64 Meg ☐ 128 Meg ☐ 256 Meg ☐ 512 Meg ☐ Other (specify density _____)

2) Location of cased DRAM assembly: ☐ United States ☐ Korea ☐ Locations other than Korea or the United States

3) Use of product: ☐ For DRAM module production ☐ For resale ☐ For other uses (specify: _____)

Item	Calendar years			January-March	
	2000	2001	2002	2002	2003
PURCHASES OF CASED DRAMS, BY ORIGIN OF DICE:[1] [2]					
U.S.-fabricated dice: Quantity (*1,000 units*)					
Value (*$1,000*)					
Korean (Samsung)-fabricated dice: Quantity (*1,000 units*)					
Value (*$1,000*)					
Korean (other firms)-fabricated dice: Quantity (*1,000 units*)					
Value (*$1,000*)					
Other-source fabricated dice: Quantity (*1,000 units*)					
Value (*$1,000*)					

[1] Please indicate your reasons for purchasing this product. If your reasons differ by source, please elaborate.

[2] Please list the name of the firm(s) from which you purchased this product. If your suppliers differ by source, please identify the source for each listed supplier.

PART II.--TRADE AND RELATED INFORMATION--*Continued*

II-25. **PURCHASES OF DRAM MODULES OTHER THAN IMPORTS.--**Other than direct imports, has your firm purchased DRAM modules since January 1, 2000? (See definitions in the instruction booklet.)

☐ No ☐ Yes.--Report such purchases below for the specified periods. **Report separately for each location of dice fabrication, location of assembly into cased DRAMs, and location of assembly into modules, and use of the purchased product combination, photocopying page as necessary.** Identify (1) the location of module assembly, (2) the location of assembly into cased DRAMs, and (3) your use of the DRAM modules, by checking one box each for category 1, 2, and 3 below.

1) Location of module assembly: ☐ United States ☐ Korea ☐ Locations other than Korea or the United States

2) Location of assembly into cased DRAMs: ☐ United States ☐ Korea ☐ Locations other than Korea or the United States

3) Use of DRAM modules: ☐ For resale ☐ For other uses (specify: _____)

Item	Calendar years			January-March	
	2000	2001	2002	2002	2003
PURCHASES OF DRAM MODULES, BY ORIGIN OF DICE:[1] [2]					
U.S.-fabricated dice: Quantity (*billion bits*)					
Value (*$1,000*)					
Korean (Samsung)-fabricated dice: Quantity (*billion bits*)					
Value (*$1,000*)					
Korean (other firms)-fabricated dice: Quantity (*billion bits*)					
Value (*$1,000*)					
Other-source fabricated dice: Quantity (*billion bits*)					
Value (*$1,000*)					

[1] Please indicate your reasons for purchasing this product. If your reasons differ by source, please elaborate.

_____

_____

_____

_____

_____

[2] Please list the name of the firm(s) from which you purchased this product. If your suppliers differ by source, please identify the source for each listed supplier. _____

_____

_____

_____

_____

_____

PART II.--TRADE AND RELATED INFORMATION--*Continued*

II-26. (a) Do you know the country of fabrication for your purchases and internal transfers of uncased DRAMs?

☐ Always ☐ Usually ☐ Sometimes ☐ Never

(b) Do you know the identity of the fabricating firm for your purchases and internal transfers of uncased DRAMs?

☐ Always ☐ Usually ☐ Sometimes ☐ Never

II-27. (a) Do you know the country of fabrication and the country of assembly for your purchases and internal transfers of cased DRAMs?

Uncased DRAM fabrication:	☐ Always	☐ Usually	☐ Sometimes	☐ Never
Cased DRAM assembly:	☐ Always	☐ Usually	☐ Sometimes	☐ Never

(b) Do you know the identity of the fabricating firm for your purchases and internal transfers of cased DRAMs?

Uncased DRAM fabrication:	☐ Always	☐ Usually	☐ Sometimes	☐ Never

II-28. (a) Do you know the country of fabrication and the country of assembly for your purchases and internal transfers of DRAM modules?

Uncased DRAM fabrication:	☐ Always	☐ Usually	☐ Sometimes	☐ Never
Cased DRAM assembly:	☐ Always	☐ Usually	☐ Sometimes	☐ Never
DRAM module assembly:	☐ Always	☐ Usually	☐ Sometimes	☐ Never

(b) Do you know the identity of the fabricating firm for your purchases and internal transfers of DRAM modules?

Uncased DRAM fabrication:	☐ Always	☐ Usually	☐ Sometimes	☐ Never

II-29. Please identify each country in which your firm or a related firm performs the following DRAM operations:

Operation	Countries
Uncased DRAM fabrication	
Cased DRAM assembly	
DRAM module assembly	

PART II.--TRADE AND RELATED INFORMATION--*Continued*

II-30. **EMPLOYMENT.--**Report the average number of production and related workers employed in your U.S. establishment(s) in which DRAMs and DRAM modules are produced. Also report the number of hours worked (paid) by such production and related workers, and the total wages paid to these employees. If your firm produced (whether for consumption or for sale) a combination of uncased DRAMs, cased DRAMs, and DRAM modules, please allocate workers, hours, and wages required to fabricate the uncased DRAMs first, then make an additional allocation for casing the DRAMs, and then a final allocation for assembling the DRAM module.

Item	Calendar years			January-March	
	2000	2001	2002	2002	2003
AVERAGE NUMBER OF PRODUCTION AND RELATED WORKERS (PRWS) PRODUCING: Uncased DRAMs					
Cased DRAMs					
DRAM modules					
HOURS WORKED BY PRWS PRODUCING: Uncased DRAMs (*1,000 hours*)					
Cased DRAMs (*1,000 hours*)					
DRAM modules (*1,000 hours*)					
WAGES PAID TO PRWS PRODUCING: Uncased DRAMs (*$1,000*)					
Cased DRAMs (*$1,000*)					
DRAM modules (*$1,000*)					

PART II.--TRADE AND RELATED INFORMATION--*Continued*

II-31. Complete the following table showing the line geometry (in microns) and wafer starts for each of your fabs for January 2000 through March 2003. Also, please indicate wafer size. If the geometry changed for a fab during a year, indicate the date of the change. If at a given time a fab was operating with two or more line geometries, indicate for each year the number of wafers processed at each geometry. Photocopy this page as necessary.

	2000	2001	2002	Jan.-Mar. 2002	Jan.-Mar. 2003
Example only Fab location/ name	6-inch wafers/ 0.35/ 130,000	6-inch/ 0.35/ 70,000 8-inch / 0.25/ 75,000 (June 10)	8-inch/ 0.25/ 150,000 8-inch/ 0.22/ 60,000 (July 1)	8-inch/ 0.25/ 70,000	8-inch/ 0.22/ 90,000 8-inch/ 0.18/ 30,000 (March 3)
Fab 1 geometry					
Fab 2 geometry					
Fab 3 geometry					
Fab 4 geometry					
Fab 5 geometry					

II-32. Please indicate the number of wafers of each density of DRAMs produced and the average number of dice per wafer prior to the probe stage, for calendar 2000 through 2002 plus the two interim periods.

Density	2000	2001	2002	Jan.-Mar. 2002	Jan.-Mar 2003
64 Megabit	wafers	wafers	wafers	wafers	wafers
	dice/wafer	dice/wafer	dice/wafer	dice/wafer	dice/wafer
128 Megabit	wafers	wafers	wafers	wafers	wafers
	dice/wafer	dice/wafer	dice/wafer	dice/wafer	dice/wafer
256 Megabit	wafers	wafers	wafers	wafers	wafers
	dice/wafer	dice/wafer	dice/wafer	dice/wafer	dice/wafer
512 Megabit	wafers	wafers	wafers	wafers	wafers
	dice/wafer	dice/wafer	dice/wafer	dice/wafer	dice/wafer

PART III.--FINANCIAL INFORMATION

Address questions on this part of the questionnaire to James Stewart (202-205-3196).

III-1. Who should be contacted regarding the requested financial information?

Company contact: _____
Name and title

_____ _____ _____
FAX No. Phone No. E-mail address

III-2. When does your fiscal year end (month and day)? _____

If your fiscal year changed during the periods for which data are being reported, explain below:

_____

III-3. Accounting basis.--The financial records of your firm are prepared on the basis of:

☐ GAAP ☐ Tax ☐ Cash ☐ Other (specify) _____

III-4. Reports and statements.--Did your firm or your parent prepare any of the statements or documents listed below during the period of the investigation? If so, please submit copies of them along with your completed questionnaire unless they are available on the World Wide Web (including the Securities and Exchange Commission's EDGAR site).

My firm or parent does ____ or does not ____ prepare financial statements (annual reports, 10-Ks). Are the above documents available on the World Wide Web?

	YES	NO
At the SEC's EDGAR site?		
At some other site? (WWW address _____)		

My firm or parent does ____ or does not ____ prepare internal profit-and-loss reports on DRAM/DRAM module operations which indicate the cost of production of DRAMs/DRAM modules.

My firm or parent does ____ or does not ____ prepare internal reports indicating the cost of production of DRAMs/DRAM modules.

III-5. Other products.--Please list any other products you produced in the facilities in which you produced DRAMs and/or DRAM modules, and provide the share of net sales accounted for by these other products in your most recent calendar year (fiscal-year information may be submitted, if calendar-year information is not available):

Product(s)	**Share of sales**
_____	_____
_____	_____
_____	_____

PART III.--FINANCIAL INFORMATION--*Continued*

III-6. **Operations on DRAMs and DRAM modules**.--Report the revenue and related cost information requested below on the DRAM/DRAM module operations of your U.S. establishment(s).[1] **Note that internal consumption and transfers to related firms must be valued at fair market value and purchases from related firms must be at cost. Please footnote any restructuring and other non-recurring items.** Provide data for your three most recently completed calendar years (fiscal-year data may be submitted, if calendar-year data are not available) in chronological order from left to right, and for the specified interim periods. **NOTE.--If your firm is only an assembler of DRAM modules or is a "fabless" producer, do not complete the table on this page.**

(*Value in $1,000*)					
Item	**☐ Calendar years or ☐ Fiscal years**			**January-March**	
	_____	_____	_____	**2002**	**2003**
NET SALES VALUES:[2] Commercial sales					
Internal consumption					
Transfers to related firms					
Total net sales values					
Cost of goods sold (including for internal consumption and transfers to related firms)					
Gross profit or (loss)					
OPERATING EXPENSES: Research and development					
Selling, general and administrative expenses					
Total operating expenses					
Operating income or (loss)					
OTHER INCOME AND EXPENSES: Interest expense					
All other expense items					
All other income items					
All other income or expenses, net					
Net income or (loss) before income taxes					
Depreciation/amortization included above					

[1] Include only your U.S. manufacturing operations, i.e., include domestic sales and export sales of DRAMs and DRAM modules produced from wafers and dice fabricated in the United States, regardless of assembly location, plus foreign dice assembled in the United States.

[2] Less discounts, returns, allowances, and prepaid freight. The values should approximate the sum of the corresponding shipment values reported in Part II of this questionnaire.

PART III.--FINANCIAL INFORMATION--*Continued*

III-7. **Detail of net sales value of DRAMs and DRAM modules**.--Please provide the detail of the net sales value which should reconcile with the trade data reported in Part II. Provide data for the three most recently completed calendar years (fiscal-year data may be submitted, if calendar-year data are not available) in chronological order from left to right and the specified interim periods.

(*Value in $1,000*)					
Item	☐ **Calendar years or** ☐ **Fiscal years**			**January-March**	
	_____	_____	_____	**2002**	**2003**
COMMERCIAL SALES:					
DRAMs made from U.S. dice: Cased in Korea					
Cased in the United States					
Cased in other countries					
DRAMs cased in the United States from dice made: In Korea by Samsung					
In Korea by other firms					
In other countries					
Uncased DRAMs[1]					
DRAM modules					
Total commercial sales[2]					
COMPANY TRANSFERS (INCLUDING INTERNAL CONSUMPTION):					
U.S.-produced cased DRAMs[3]					
U.S.-produced uncased DRAMs[4]					
DRAM modules					
Total company transfers[2]					
Total net sales[2]					

[1] List your customers that purchased uncased DRAMs: _____

[2] The totals should agree with the commercial sales, the combined transfers and internal consumption, and the total net sales in section III-6 for operations of DRAMs and DRAM modules.

[3] Not used in the production of DRAM modules included in net commercial sales above.

[4] Not used in the production of cased DRAMs or DRAM modules included in net commercial sales above.

PART III.--FINANCIAL INFORMATION--*Continued*

III-8. **Capital expenditures, research and development expenditures, and asset values**.--Report your firm's capital expenditures and research and development expenditures on DRAMs/DRAM modules, and the values of the property, plant, and equipment used in the production of DRAMs/DRAM modules. Provide data for your three most recently completed calendar years (fiscal-year data may be submitted, if calendar-year data are not available) in chronological order from left to right, and for the specified interim periods.

(*Value* in $1,000)					
Item	☐ Calendar years or ☐ Fiscal years			January-March	
	_____	_____	_____	**2002**	**2003**
Capital expenditures:					
Uncased DRAMs					
Cased DRAMs					
DRAM modules					
Total					
Research and development expenditures:					
Uncased DRAMs					
Cased DRAMs					
DRAM modules					
Total					
Property, plant, and equipment:					
Original cost:					
Uncased DRAMs					
Cased DRAMs					
DRAM modules					
Total					
Book value:					
Uncased DRAMs					
Cased DRAMs					
DRAM modules					
Total					

PART III.--FINANCIAL INFORMATION--*Continued*

III-9. Since January 1, 2000, has your firm experienced any actual negative effects on its return on investment or its growth, investment, ability to raise capital, existing development and production efforts (including efforts to develop a derivative or more advanced version of the product), or the scale of capital investments as a result of imports of DRAMs or DRAM modules from Korea? If your answer differs with respect to imports of Korea (Samsung) versus Korea (other firms), please so specify. Attach additional pages discussing specifics, as needed.

☐ No ☐ Yes--My firm has experienced actual negative effects as follows:

Cancellation or rejection of expansion projects ☐

Denial or rejection of investment proposal ☐

Reduction in the size of capital investments ☐

Rejection of bank loans ☐

Lowering of credit rating ☐

Problem related to the issue of stocks or bonds ☐

Other (specify) _____

III-10. Does your firm anticipate any negative impact of imports of DRAMs and DRAM modules from Korea? If your answer differs with respect to imports of Korea (Samsung) versus Korea (other firms), please so specify.

☐ No ☐ Yes--My firm anticipates negative effects as follows:

_____

_____

_____

PART IV.--PRICING AND RELATED INFORMATION

Information on this part of the questionnaire can be obtained from John N. Giamalva (202-205-2785).

IV-1. Who should be contacted regarding the requested pricing and related information?

Company contact: _____
Name and title

_____ _____
Phone No. E-mail address

Section IV-A.--PRICE DATA

This section requests monthly price and quantity data concerning your firm's U.S. commercial shipments to unrelated U.S. customers of the following DRAM products during January 2000-March 2003:

***Cased DRAMs*:**

***Product 1*.–64 megabit PC100 and PC133 SDRAM**
***Product 2*.–128 megabit PC100 and PC133 SDRAM**
***Product 3*.–256 megabit PC100 and PC133 SDRAM**
***Product 4*.–128 megabit DDR SDRAM**
***Product 5*.–256 megabit DDR266 SDRAM**

***DRAM modules*:**

***Product 6*.–64 Megabyte PC100 and PC133 memory module**
***Product 7*.–128 Megabyte PC100 and PC133 memory module**
***Product 8*.–256 Megabyte DDR266 SDRAM memory module**

PART IV.--PRICING AND RELATED INFORMATION--*Continued*

Section IV-A.--PRICE DATA--*Continued*

IV-A-1. **Cased DRAMs sold in 2000 and 2001.--COPY THIS PAGE AS NECESSARY.** Complete a separate page for each of the specified cased DRAM products **assembled and sold by your firm in the United States**. Please identify the product by product number and report separately for each combination of fabrication source and customer type.

Product: ☐ **Product 1**[1] ☐ **Product 2**[1] ☐ **Product 3**[1] ☐ **Product 4**[1] ☐ **Product 5**[1]

Note: If you reported sales of this product in the preliminary questionnaire response, and the data have not changed, check here and skip to the next page _____

Fabricated in: ☐ **United States** ☐ **Korea by Samsung** ☐ **Korea by others** ☐ **Other countries**

Customer type: ☐ **PC OEMs** ☐ **Other OEMs** ☐ **All other sales**

(*Quantity* in units, *value* in dollars)					
Month	**Quantity**	**Value**	**Month**	**Quantity**	**Value**
2000:			**2001:**		
Jan.			Jan.		
Feb.			Feb.		
Mar.			Mar.		
Apr.			Apr.		
May			May		
June			June		
July			July		
Aug.			Aug.		
Sep.			Sep.		
Oct.			Oct.		
Nov.			Nov.		
Dec.			Dec.		

[1] If your product does not exactly meet the product specifications but is competitive with the specified product, provide a description of your product:

_____

_____

PART IV.--PRICING AND RELATED INFORMATION--*Continued*

Section IV-A.--PRICE DATA--*Continued*

IV-A-2. **Cased DRAMs sold in 2002 and January-March 2003.--COPY THIS PAGE AS NECESSARY.** Report separately for each of the specified cased DRAM products **assembled and sold by your firm in the United States**. Please identify the product by product number and report separately for each combination of fabrication source and customer type.

Product: ☐ **Product 1**[1] ☐ **Product 2**[1] ☐ **Product 3**[1] ☐ **Product 4**[1] ☐ **Product 5**[1]

Note: If you reported sales of this product in the preliminary questionnaire response, and the data have not changed, check here and report only for October 2002-March 2003 _____

Fabricated in: ☐ **United States** ☐ **Korea by Samsung** ☐ **Korea by others** ☐ **Other countries**

Customer type: ☐ **PC OEMs** ☐ **Other OEMs** ☐ **All other sales**

(*Quantity* in units, *value* in dollars)					
Month	**Quantity**	**Value**	**Month**	**Quantity**	**Value**
2002:			**2003:**		
Jan.			Jan.		
Feb.			Feb.		
Mar.			Mar.		
Apr.					
May					
June					
July					
Aug.					
Sep.					
Oct.					
Nov.					
Dec.					

[1] If your product does not exactly meet the product specifications but is competitive with the specified product, provide a description of your product:

_____

_____

PART IV.--PRICING AND RELATED INFORMATION--*Continued*

Section IV-A.--PRICE DATA--*Continued*

IV-A-3. **DRAM modules sold in 2000 and 2001--COPY THIS PAGE AS NECESSARY.** Complete a separate page for each of the specified DRAM modules **assembled and sold by your firm in the United States. If your firm neither fabricates nor cases DRAMs in the United States, please skip this question.** Please identify the product by product number and report separately for each combination of fabrication source, cased DRAM assembly source, and customer type.

Product: ☐ **Product 6**[1] ☐ **Product 7**[1] ☐ **Product 8**[1]

Note: If you reported sales of this product in the preliminary questionnaire response, and the data have not changed, check here and skip to next page _____

Fabricated in: ☐ **United States** ☐ **Korea by Samsung** ☐ **Korea by others** ☐ **Other countries**

Country where dice were assembled into cased DRAMs: ☐ **United States** ☐ **Korea** ☐ **Other countries**

Customer type: ☐ **PC OEMs** ☐ **Other OEMs** ☐ **All other sales**

(*Quantity* in units, *value* in dollars)					
Month	**Quantity**	**Value**	**Month**	**Quantity**	**Value**
2000:			**2001:**		
Jan.			Jan.		
Feb.			Feb.		
Mar.			Mar.		
Apr.			Apr.		
May			May		
June			June		
July			July		
Aug.			Aug.		
Sep.			Sep.		
Oct.			Oct.		
Nov.			Nov.		
Dec.			Dec.		

[1] If your product does not exactly meet the product specifications but is competitive with the specified product, provide a description of your product:

_____

_____

PART IV.--PRICING AND RELATED INFORMATION--*Continued*

Section IV-A.--PRICE DATA--*Continued*

IV-A-4. DRAM modules sold in 2002 and January-March 2003--COPY THIS PAGE AS NECESSARY. Report separately for each of the specified DRAM modules **assembled and sold by your firm in the United States. If your firm neither fabricates nor cases DRAMs in the United States, please skip this question.** Please identify the product by product number and report separately for each combination of fabrication source, cased DRAM assembly source, and customer type.

Product: ☐ **Product 6**[1] ☐ **Product 7**[1] ☐ **Product 8**[1]

Note: If you reported sales of this product in the preliminary questionnaire response, and the data have not changed, check here and report only for October 2002-March 2003.

Fabricated in: ☐ **United States** ☐ **Korea by Samsung** ☐ **Korea by others** ☐ **Other countries**

Country where dice were assembled into cased DRAMs: ☐ **United States** ☐ **Korea** ☐ **Other countries**

Customer type: ☐ **PC OEMs** ☐ **Other OEMs** ☐ **All other sales**

(*Quantity* in units, *value* in dollars)					
Month	**Quantity**	**Value**	**Month**	**Quantity**	**Value**
2002:			**2003:**		
Jan.			Jan.		
Feb.			Feb.		
Mar.			Mar.		
Apr.					
May					
June					
July					
Aug.					
Sep.					
Oct.					
Nov.					
Dec.					

[1] If your product does not exactly meet the product specifications but is competitive with the specified product, provide a description of your product:

_____

_____

PART IV.--PRICING AND RELATED INFORMATION--*Continued*

Section IV-B.--PRICE-RELATED QUESTIONS

IV-B-1. Please describe how your firm determines the prices that it charges for sales of DRAMs or DRAM modules in the U.S. market (transaction by transaction negotiation, contracts for multiple shipments, set price lists, etc.). If your firm issues price lists, please include a copy of a recent price list with your submission. If your price list is large, please submit sample pages.

IV-B-2. Please describe your firm's discount policy (quantity discounts, annual volume discounts, etc.).

IV-B-3. What are your firm's typical sales terms for its U.S.-produced DRAMs or DRAM modules in the U.S. market (e.g., 2/10 net 30 days)? _____ On what basis are your prices of domestic DRAMs or DRAM modules usually quoted (e.g., f.o.b. warehouse, or delivered)? _____

IV-B-4. Approximately what percentage of your firm's U.S. sales of its U.S.-produced DRAMs or DRAM modules are on a contract (____ percent) vs. spot sales (____ percent) basis? If you sell on a contract basis, please answer the following questions with respect to provisions of a typical contract.

(a) What is the average duration of a contract? _____

(b) How frequently are contracts renegotiated? _____

(c) Does the contract fix quantity, price, or both? _____

(d) Does the contract have a meet or release provision? _____

(e) What are the standard quantity requirements, if any? _____

(f) What is the price premium for sub-minimum shipments? ____ percent

(g) Please describe the relationship between spot prices and contract prices since January 1, 2000

PART IV.--PRICING AND RELATED INFORMATION--*Continued*

Section IV-B.--PRICE-RELATED QUESTIONS--*Continued*

IV-B-5. If you sell on a contract basis, describe the impact of spot pricing on contract prices;

(a) when contract prices are negotiated _____

_____

_____

(b) within the contract period _____

_____

_____

IV-B-6. (a) Has your firm entered into any long-term agreements for the supply of DRAMs or DRAM modules? If yes, please report the terms of these supply agreements (i.e., pricing, volume, duration), the share of your total sales accounted for by these long-term agreements, and the firms and locations involved.

_____

_____

(b) Do your customers with more than one location negotiate a single contract or a single price for all locations. No _____ Yes _____ --If Yes, please explain whether this is true for all multi-location customers or only for some, and if only for some, please elaborate on the type(s) of customers involved.

_____

_____

IV-B-7. What is the average lead time between a customer's order and the date of delivery for your firm's sales of DRAMs or DRAM modules? _____

IV-B-8. What is the approximate percentage of the total delivered cost of DRAMs or DRAM modules that is accounted for by U.S. inland transportation costs? _____ percent. Who generally arranges the transportation to your customers' locations? Your firm ____ or purchaser ____ (check one). What proportion of your sales occur within 100 miles of your storage or production facility? ___ _ percent. 101 to 1,000 miles? _____ percent. Over 1,000 miles? _____ percent.

IV-B-9. What is the geographic market area in the United States served by your firm's DRAMs or DRAM modules?

_____

PART IV.--PRICING AND RELATED INFORMATION--*Continued*

Section IV-B.--PRICE-RELATED QUESTIONS--*Continued*

IV-B-10. a) Please describe a typical business cycle in the DRAMs market (e.g., determinants of the cycle, the relationship of capacity to demand, and the pricing practices of individual firms). Does the DRAMs business cycle affect your production of DRAMs or DRAM modules? If so, how?

b) Is the DRAMs market affected by seasonal cycles (e.g., the holiday season, back-to-school season, etc.)? If so, how does this affect your production of DRAMs or DRAM modules?

IV-B-11. Describe how easily your firm can shift its sales of DRAMs or DRAM modules between the U.S. market and alternative country markets. In your discussion, please describe any contracts, other sales arrangements, or other constraints (including any third-country trade barriers such as tariffs, quotas, or other non-tariff barriers) that would prevent or retard your firm from shifting DRAMs or DRAM modules between the U.S. and alternative country markets within a 12-month period.

IV-B-12. What other products may be substitutes for DRAMs or DRAM modules? Please report the application(s) in which such substitution is possible.

IV-B-13. Describe the end uses of the DRAMs or DRAM modules that you manufacture. For each end use product, what percentage of the total cost is accounted for by DRAMs or DRAM modules?

PART IV.--PRICING AND RELATED INFORMATION--*Continued*

Section IV-B.--PRICE-RELATED QUESTIONS--*Continued*

IV-B-14. How has the demand within the United States (and outside the United States if known) for DRAMs or DRAM modules changed since January 1, 2000? What were the principal factors affecting changes in demand?

IV-B-15. Have there been any significant changes in the product range or marketing of DRAMs or DRAM modules in the past five years?

☐ No ☐ Yes--Please describe.

IV-B-16. Please report the approximate date your firm began selling each of the following devices in commercial quantities in the U.S. market. If your answer differs by customer type, please explain

128 Megabit SDRAMs:

256 Megabit SDRAMs:

Double Data Rate SDRAMs:

1 Gigabit SDRAMs:

IV-B-16. Does your firm sell DRAMs or DRAM modules over the internet?

☐ No ☐ Yes–Please describe, noting the estimated percentage of your firm's total sales of DRAMs or DRAM modules in 2002 accounted for by internet sales.

PART IV.--PRICING AND RELATED INFORMATION--*Continued*

Section IV-B.--PRICE-RELATED QUESTIONS--*Continued*

Please note: Subject Korean DRAMs and DRAM modules are those with dice fabricated in Korea. U.S.-produced DRAMs and DRAM modules are those with U.S.-fabricated dice, and those with dice fabricated in a third country and then cased in the United States. Nonsubject DRAMs and DRAM modules are those with dice fabricated in a third country and not cased in the United States.
If your answers to any questions in this section vary by Korean producer (e.g. Hynix vs Samsung) please answer separately for each producer.

IV-B-17. Please report the value of your firm's total U.S. commercial shipments of DRAMs and DRAM modules assembled and sold by your firm in the United States that were made to each of the following customer types during 2002:

Customer type	Individual DRAMs	DRAM Modules
PC OEMs		
Other OEMs		
All other sales (distributors etc.)		
Total	$	$

IV-B-18. What percentage of the total cost of a DRAM module is accounted for by the cost of the DRAMs?

_____

IV-B-19. Are the U.S.-produced and subject Korean DRAMs or DRAM modules used interchangeably (i.e., can they physically be used in the same applications)?

☐ Yes ☐ No--Please explain.

_____

_____

IV-B-20. Are the U.S.-produced and NONSUBJECT imported DRAMs or DRAM modules generally used interchangeably?

☐ Yes ☐ No--Please explain, by country.

_____

_____

PART IV.--PRICING AND RELATED INFORMATION--*Continued*

Section IV-B.--PRICE-RELATED QUESTIONS--*Continued*

Please note: Subject Korean DRAMs and DRAM modules are those with dice fabricated in Korea. U.S.-produced DRAMs and DRAM modules are those with U.S.-fabricated dice, and those with dice fabricated in a third country and then cased in the United States. Nonsubject DRAMs and DRAM modules are those with dice fabricated in a third country and not cased in the United States.
If your answers to any questions in this section vary by Korean producer (e.g. Hynix vs Samsung) please answer separately for each producer.

IV-B-21. Are NONSUBJECT imported DRAMs or DRAM modules and subject Korean DRAMs or DRAM modules used interchangeably?

☐ Yes ☐ No--Please explain, by country.

IV-B-22. Are there any differences in product characteristics or sales conditions between U.S.-produced DRAMs or DRAM modules and subject Korean DRAMs or DRAM modules that are a significant factor in your firm's sales of DRAMs or DRAM modules?

☐ No ☐ Yes--Please describe any such advantages or disadvantages of the domestic product vis-a-vis the imported product (e.g., quality, availability, transportation network, product range, technical support, etc.).

IV-B-23. Are there any differences in product characteristics or sales conditions between U.S.-produced DRAMs or DRAM modules and NONSUBJECT imported DRAMs or DRAM modules that are a significant factor in your firm's sales of DRAMs or DRAM modules?

☐ No ☐ Yes--Please describe any such advantages or disadvantages of the domestic product vis-a-vis the nonsubject imported product.

PART IV.--PRICING AND RELATED INFORMATION--*Continued*
Section IV-B.--PRICE-RELATED QUESTIONS--*Continued*

IV-B-24. Are there any differences in product characteristics or sales conditions between NONSUBJECT imported DRAMs or DRAM modules and subject Korean DRAMs or DRAM modules that are a significant factor in your firm's sales of DRAMs or DRAM modules?

☐ No ☐ Yes--Please describe, by country, any such advantages or disadvantages of the nonsubject imported product vis-a-vis the subject Korean product.

IV-B-25. Using specific applications as examples where appropriate, discuss the substitutability of:
a) DRAMs with different addressing modes (EDO, synchronous, DDR, Rambus, etc.)

b) Commodity DRAMs with specialty DRAMs (SGRAM, VRAM, WRAM, etc.)

c) DRAMs with differing densities (e.g. viability of substituting four 64 Meg DRAMs in an application for one 256 Meg DRAM).

d) DRAMs with differing speeds (e.g. viability of substituting PC100 SDRAMs for PC133 SDRAMs or DDR266 SDRAMs for DDR333 SDRAMs).

PART IV.--PRICING AND RELATED INFORMATION--*Continued*

Section IV-B.--PRICE-RELATED QUESTIONS--*Continued*

IV-B-26. a) Do the U.S. firms to which you sell DRAMs or DRAM modules require that your firm be qualified before they will purchase DRAMs or DRAM modules from you? If yes, please describe, in detail, the qualification process. Include in your description the steps required, the time of the process, the type of DRAM involved, and the types of customers (PC OEM, other OEM, distributor, etc.) that require qualification.

b) Subsequent to qualification of your firm, do the U.S. firms to which you sell DRAMs or DRAM modules require that DRAMs be qualified in a specific application? If yes, please describe, in detail, the qualification process. Include in your description, the steps required, the time of the process, the type of DRAM involved, and the types of customers (PC OEM, other OEM, distributor, etc.), that require qualification in a specific application.

c) Since January 1, 2000, has your firm ever failed to qualify to supply DRAMs or DRAM modules to a U.S. customer? Yes ____ No ____. If yes, please give the date, customer name, type of DRAM, and the reason for the failure to qualify. Please also note whether your firm failed to qualify for all applications, or qualified for some applications but not others. If your firm attempted to qualify at a later date, please report the result of that attempt.

PART IV.--PRICING AND RELATED INFORMATION--*Continued*
Section IV-C.--COMPETITION FROM IMPORTS--LOST REVENUES

DO NOT REPEAT ALLEGATIONS MADE IN THE PETITION OR IN THE PRELIMINARY PHASE QUESTIONNAIRE. (Note: petitioner may only provide allegations involving quotes made AFTER the filing of its questionnaire in the preliminary phase of the investigations.)

Please report separately for products fabricated in Korea by Samsung and those fabricated in Korea by other firms.

Since January 1, 2000: To avoid losing sales to competitors selling DRAMs or DRAM modules from Korea, did your firm:

Reduce prices ☐ Yes ☐ No

Roll back announced price increases ☐ Yes ☐ No

If yes, please furnish as much of the following information as possible for each affected transaction. Document such allegations of lost revenues whenever possible (documentation could include copies of invoices, sales reports, or letters from customers). **Please note that the Commission may contact the firms named to verify the allegations reported**.

Customer name, contact person, phone and fax numbers
Specific product(s) involved
Date of your initial price quotation
Quantity involved
Your initial ***rejected*** price quotation (total delivered value)
Your ***accepted*** price quotation (total delivered value)
The country of origin of the competing imported product
The competing price quotation of the imported product (total delivered value)

Customer name, contact person, phone and fax numbers	Product	Date of quote	Quantity (*UNITS*)	Initial rejected U.S. price (total value--*dollars*)	Accepted U.S. price (total value--*dollars*)	Korean fabricator	Competing import price (total value--*dollars*)

PART IV.--PRICING AND RELATED INFORMATION--*Continued*
Section IV-D.--COMPETITION FROM IMPORTS--LOST SALES

DO NOT REPEAT ALLEGATIONS MADE IN THE PETITION OR IN THE PRELIMINARY PHASE QUESTIONNAIRE. (Note: petitioner may only provide allegations involving quotes made AFTER the filing of their questionnaire in the preliminary phase of the investigations.)

Please report separately for products fabricated in Korea by Samsung and those fabricated in Korea by other firms.

Since January 1, 2000: Did your firm lose sales of DRAMs or DRAM modules to imports of these products from Korea?

☐ Yes ☐ No

If yes, please furnish as much of the following information as possible for each affected transaction. Document such allegations of lost sales whenever possible (documentation could include copies of invoices, sales reports, or letters from customers). **Please note that the Commission may contact the firms named to verify the allegations reported**.

Customer name, contact person, phone and fax numbers
Specific product(s) involved
Date of your price quotation
Quantity involved
Your rejected price quotation (total delivered value)
The country of origin of the competing imported product
The accepted price quotation of the imported product (total delivered value)

Customer name, contact person, phone and fax numbers	Product	Date of quote	Quantity (*UNITS*)	Rejected U.S. price (total value--*dollars*)	Korean fabricator	Accepted import price (total value--*dollars*)